

MULTI-DIE MODULE AND METHOD THEREOF**ABSTRACT OF THE DISCLOSURE**

A multi-die module is electrically connected to both an unpackaged die and a packaged die as disclosed herein. The multi-die module has a footprint that is the same as conventional multi-die packages, which do not include packaged die, thereby allowing the multi-die module to be interchangeable with conventional multi-die packages. In one embodiment, the unpackaged die is a graphics processor, and the packaged die is a standard memory that has been burned in, functionally tested, and speed rated.

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